

Supplementary Materials

# Highly Thermal Conductive and Electrical Insulating Epoxy Composites with a Three-Dimensional Filler Network by Sintering Silver Nanowires on Aluminum Nitride Surface

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**Citation:** Lee, W.; Kim, J. Highly Thermal Conductive and Electrical Insulating Epoxy Composites with a Three-Dimensional Filler Network by Sintering Silver Nanowires on Aluminum Nitride Surface. *Polymers* **2021**, *13*, 694.  
<https://doi.org/10.3390/polym13050694>

Academic Editor Angels Serra

Received: 9 February 2021

Accepted: 21 February 2021

Published: date

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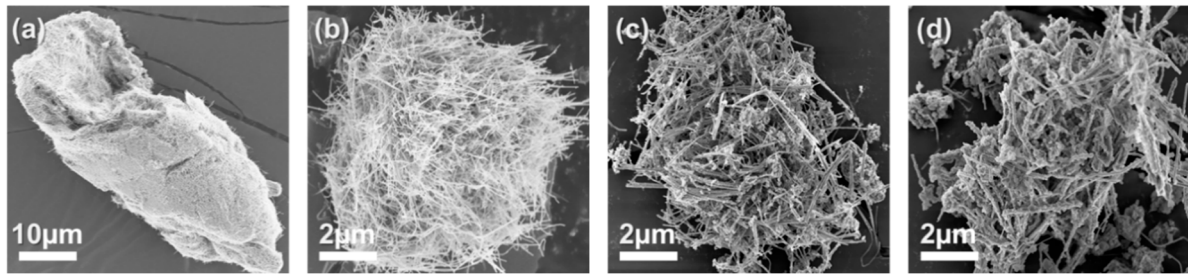


Figure S1. FE-SEM images of AA filler along AIN-to-AgNW ratio (a) 1:2, (b) 1:1, (c) 2:1, (d) 3:1.

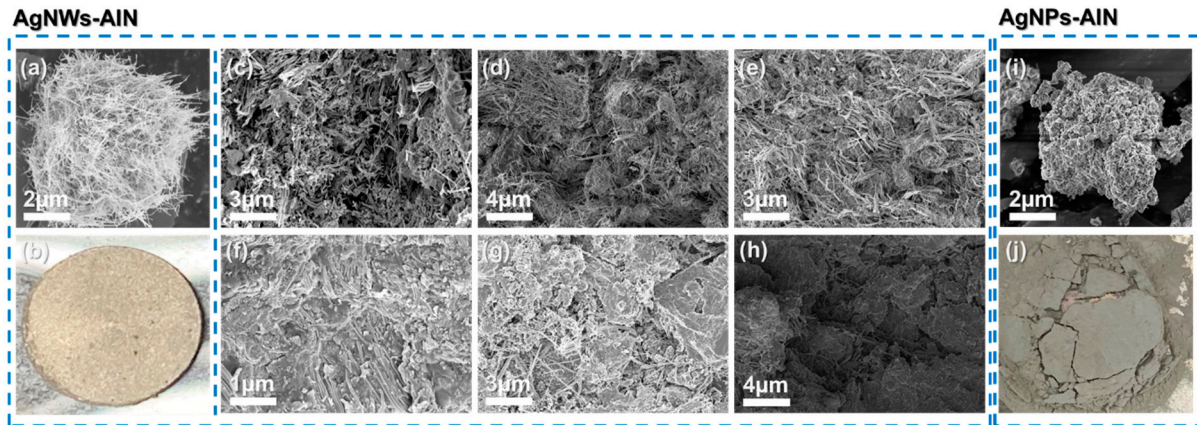


Figure S2. FE-SEM images of (a) AA filler and (b) 3D network by sintered AA fillers. Cross-sectional images of 3D network ((c) 30s, (d) 1 min, and (e) 2 min) and composites ((f) 30 s, (g) 1 min, and (h) 2 min) according to hot-pressing time. Images of (i) AgNPs-AIN and corresponding (h) network by sintered AgNPs-AIN.

Table S1. Comparison of composites thickness according to filler ratio.

Composites	AIN-to-AgNW Weight Ratio	Thickness (mm)
400-1:2	1:2	1.243
400-1:1	1:1	1.551
400-2:1	2:1	1.856
400-3:1	3:1	2.08